

Specification

Printed:
Revision:
(GB) Version:

Ph.: +49 6061 96925-0

SJM-40W NH(IMT)

06.06.2016 01.06.2016 5.0

Trade Name: SJM-40W NH(IMT)

1. Company Address: Almit GmbH

Unterer Hammer 3 Fax: +49 6061 96925-18

(D) 64720 Michelstadt - near Frankfurt

2. Validity: This specification is specified for:

Almit-Solder-Paste SJM-40W NH(IMT)

Delivered by Almit GmbH to: _____

3. Diameter & Allowance:

Weight	500g	500g	700g	1000g	0
Allowance			-0, +10g		

4. Deliverable Reel Size:

Metal Name	Solidus °C	Liquidus °C	Specific Gravity
SJM-40	221	227	7.4

5. Physical Properties:

Test	Characteristics	Test Methods
Metal Content	88.0 ± 1.0	IPC-TM-650 2.2.20
Silver Chromate	pass	IPC-TM-650 2.3.33
Copper Mirror Test	pass	IPC-TM-650 2.3.32
SIR (85°C, 85%, 168hr) (Ω)	≥ 1x10 ⁸	IPC-TM-650 2.6.3.3
Corrosion Test	pass	IPC-TM-650 2.6.15
Flux materials composition	RO	J-STD-004B
Quantitative Halide	L0 < 0.0%	IPC-TM-650 2.3.28.1
Fluorides By Spot Test	pass	IPC-TM-650 2.3.35.1

6. Characterisitcs:

Composition				Components			
	Sn	Ag		Sb	Bi	Si	
Standard	Rest	4.0	5	3.0	2.0	≤0.25	
Composition				Components			
Standard							

7. Solder Powder Size & Distribuon:

% of Sample by Weight – Nominal Size

Type not larger than		less than 1%	at least 80%	at most 10%
		larger than	between	less than
Type 4 (W)	40 Microns	38 Microns	20 - 38 Microns	20 Microns

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8. Lot-Size: A single lot contains 500kg which is the amount of one melting.

9. Quality and Inspecon:

Inspecon items are applied to each lot as follows:

Test No.	Inspection Item	Contents	Sta	andard
1	Appearance	Color	Comparison with Limit Specimer	
2	Weight	Net Weight	-0;+10	(g)
3	Solder Powder Size	20 - 38 μm (W)	94 ≤	(wt%)
		Sn	Rest	(wt%)
4	Metal Composition	Ag	4.0 ± 0.2	(wt%)
4	Metal Composition	Bi	2.0 ± 0.2	(wt%)
		Sb	3.0 ± 0.2	(wt%)
5		Flux Content	12.0 ± 0.5	(wt%)
6	7 Characteristics	Solder Balling Test	Comparison w	ith Limit Specimen
7		Viscosity (Spiral type, 10rpm, 25°C) (IPC-650-2.4.34.3)	210000 ± 30000 210 ± 30	(cps) (Pa•s)
8		Solderability on Cu-Plate	Comparison w	ith Limit Specimen
9		Dryness	· ·	uld be easily removed test specimen.

^{*}Straight lines of solder paste are printed on a JIS-2 type substrate then reflowed. The reflowed solder is examined with a stereo microscope at 30X magnification. No more than 2 solder balls larger than one fifth the size of the pattern gap is allowed per gap.

10. Packing:

Individual Package		C	Outer Package
Unit	Packing	Unit	Packing
500g	Polyethylene bottle	10kg; 20kg	
500g	6 oz Catridge	10kg	
700g	Proflow Cassette	7kg ; 14kg	Cardboard Box
1000g	12 oz Catridge	15kg	

11. Identification:

	Polyethylene bottle	Cardboard
Name	Almit-Solder-Paste SJM-40W NH(IMT)	same as the left
Lot Nr.	(Ex.) 120119-9	dto.
Solder Powder Size	20 - 38 μm	dto.
Date of Mfg.	(Ex.) 19.01.2012	dto.
Net Weight	(Ex.) 500g	dto.
Maker	Nihon Almit Co. Ltd.	dto.

10. Maker Address: Nihon Almit Co. Ltd.

Almit Bldg., 2-14-2 Yayoicho, Nakano-ku, Tokyo, Japan

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11.	In case of changing	this specification it should be accepted by:
	Signature	Date

12. This product is manufactured, using all guaranteed materials according to the legal law regulations.

13. Shelf Life:

Up to 6 months from the manufactured date (lot number).

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